

Abstract of the Invention

A tin electroplating solution, characterized in that it has a pH of 1.5 to 6.0 and comprises the following components: (1) 5 to 60 g/L of a tin (II) ion, (2) a complexing agent, (3) a surfactant and (4) 0.01 to 0.5 g/L of a bismuth (III) ion; and a method for the tin plating of electronic parts or the like which comprises using the tin electroplating solution are disclosed. The tin electroplating solution exhibits a soldering wettability being comparable with or superior to a conventional tin-lead alloy (solder) without the use of hazardous lead or an organic brightening agent.